

ABSTRACT OF THE DISCLOSURE

[00120] The present invention provides co-curable compositions in which an anionically or cationically reactive component, such as an epoxy or episulfide resin component; a free radical polymerizable component; and a cross linking component, where the cross linking component is reactive with each of the anionically or cationically reactive component and the free radical polymerizable component through functionalization with at least one group reactive through an anionic or cationic mechanism and at least one group reactive through a free radical mechanism. The invention further provides methods of preparing such compositions, methods of applying such compositions to substrate surfaces, and assemblies prepared therewith for connecting microelectronic circuitry.